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(54) **PACKAGE SUBSTRATE AND FABRICATING METHOD THEREOF**

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(57) **ABSTRACT**

A package substrate is provided, in which a first circuit structure is formed on a core board body, and a second circuit structure is formed on the first circuit structure. A second insulating layer of the second circuit structure is made of an ABF material that is different from a material forming a first insulating layer of the first circuit structure, so that a second circuit layer with fine lines/spaces can be formed by the ABF material of the second insulating layer to achieve a purpose of multi-layer fine lines.

